TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251029004.2

Qualification of MIHO using qualified Process Technology for select devices

Change Notification / Sample Request

Date: October 31, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251029004.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TAS6424EQDKQRQ1	NULL
TAS6422EQDKQRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251029004.2	**PCN Date:**	October 31, 2025
Title:	Qualification of MIHO using qualified Process Technology for select devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	April 29, 2026	**Sample requests accepted until:**	December 30, 2025*

***Sample requests received after December 30, 2025 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of MIHO using the LBC7 qualified process technology for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
RFAB	LBC7	300 mm	MIHO	LBC7	200 mm

Construction differences are as follows:

	RFAB	MIHO
Final Wafer Thickness	775 um	752 um

Qual details are provided in the Qual Data Section.

Reason for Change:

Adding a 2nd source facility for supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
MIHO	**MH6**	**JPN**	**Miho, Ibaragi-ken**

Sample product shipping label (not actual product label):

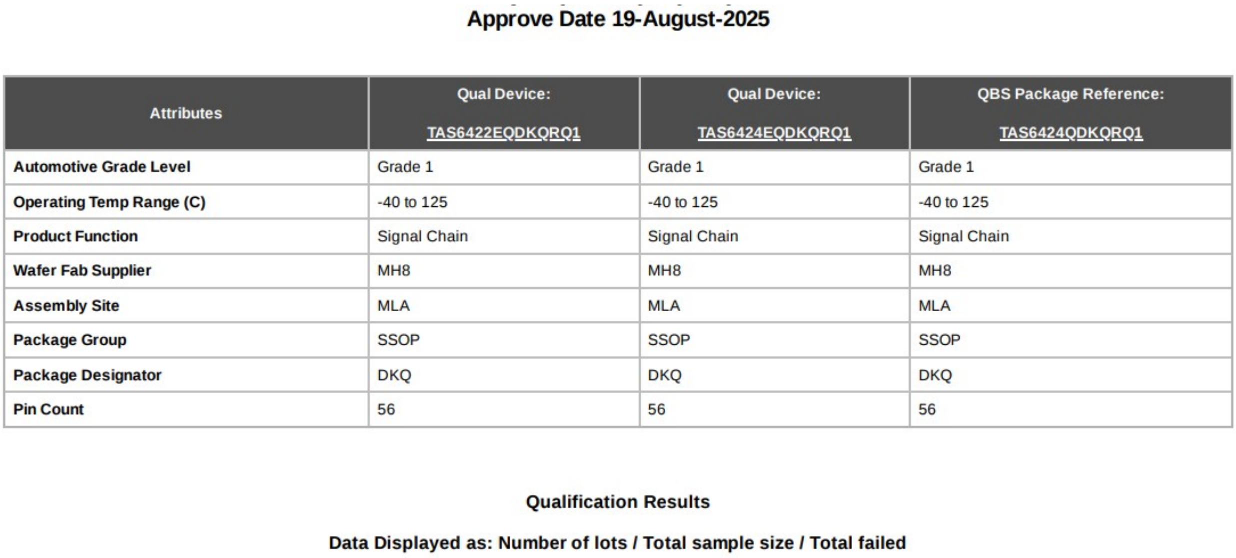
TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected

TAS6422EQDKQRQ1 TAS6424EQDKQRQ1 TAS6424MEQDKQRQ1

For alternate parts with similar or improved performance, please visit the product page on TI.com



Approve Date 19-August-2025

Attributes	Qual Device: TAS6422EQDKQRQ1	Qual Device: TAS6424EQDKQRQ1	QBS Package Reference: TAS6424QDKQRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Signal Chain
Wafer Fab Supplier	MH8	MH8	MH8
Assembly Site	MLA	MLA	MLA
Package Group	SSOP	SSOP	SSOP
Package Designator	DKQ	DKQ	DKQ
Pin Count	56	56	56

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TAS6422EQDKQRQ1	Qual Device: TAS6424EQDKQRQ1	QBS Reference: TAS6424QDKQRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	-	3/0/4[1]
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	-	-	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	-	-	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/1
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	-	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	-	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	-	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	-	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	-	3/209/2[2]
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	-	-	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	-	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	-	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	-	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	-	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/2
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	-	-	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	-	-	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	-	-	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	-	-	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	-	-	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	-	-	3/208/2[3]
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	-	-	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	-	-	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	-	-	3/9/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TAS6422EQDKQRQ1	Qual Device: TAS6424EQDKQRQ1	QBS Reference: TAS6424QDKQRQ1
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	-	-	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	-	-	3/9/0
PTC	A5.1	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	-	1/45/0
PTC	A5.2	JEDEC JESD22-A105	1	45	PTC	-40/125C	2000 Cycles	-	-	1/45/2[4]
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	175C	500 Hours	-	-	-
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	-	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	-	3/132/9[5]
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	175C	1000 Hours	-	-	-
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	-	3/3/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TAS6422EQDKQRQ1 is qualified at MSL3 260C
- Qual Device TAS6424EQDKQRQ1 is qualified at MSL3 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2410-003

Product Attributes

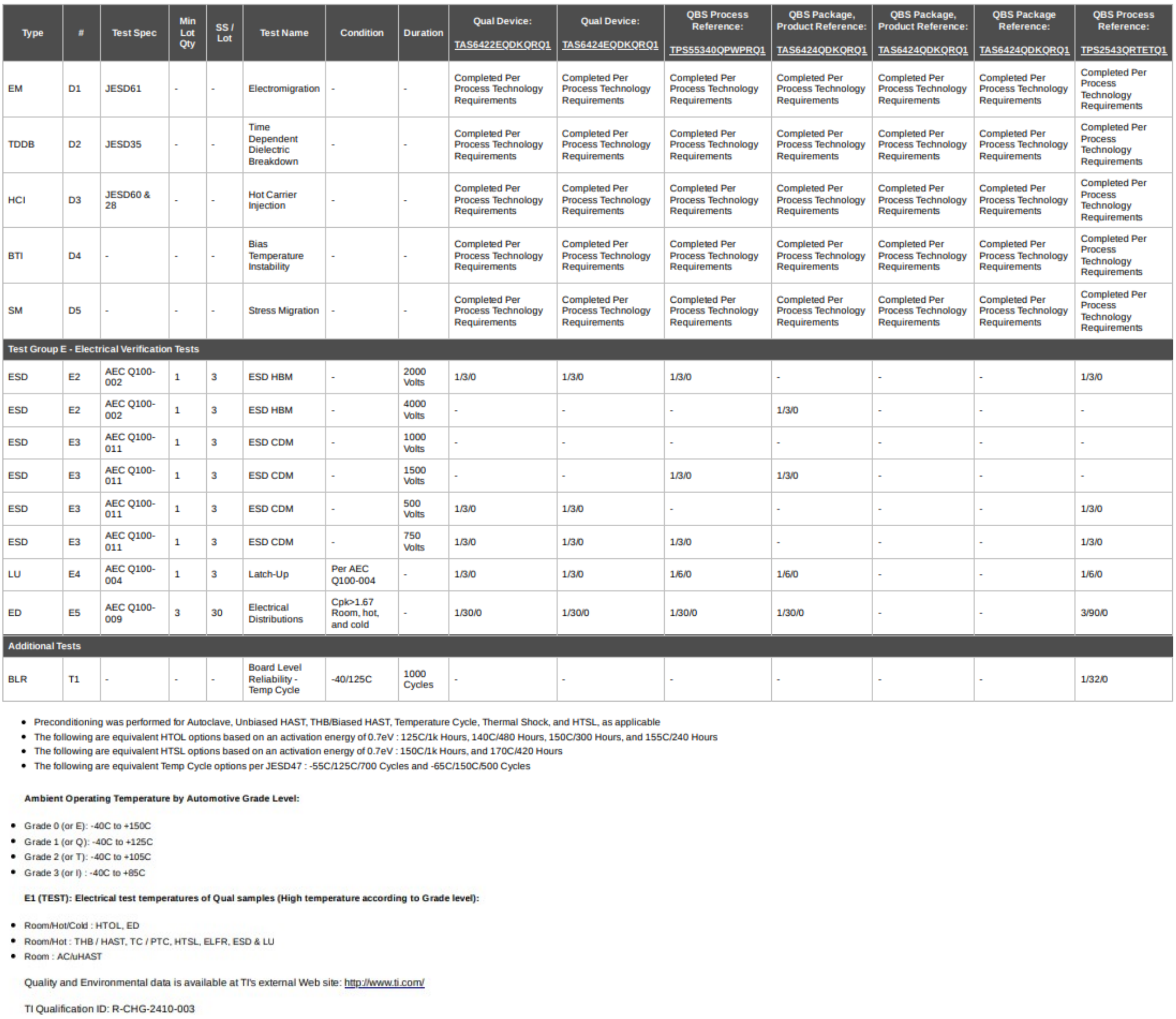
Attributes	Qual Device: TAS6422EQDKQRQ1	Qual Device: TAS6424EQDKQRQ1	QBS Process Reference: TPS55340QPWPRQ1	QBS Package, Product Reference: TAS6424QDKQRQ1	QBS Package, Product Reference: TAS6424QDKQRQ1	QBS Package Reference: TAS6424QDKQRQ1	QBS Process Reference: TPS2543QRTETQ1	QBS Product Reference: TAS6421QDKQRQ1	QBS Product Reference: TAS6424RQDKQRQ1	QBS Process Reference: TAS6424QDKQRBO
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Power Management	Signal Chain	Signal Chain	Signal Chain	Power Management	Signal Chain	Signal Chain	Signal Chain
Wafer Fab Supplier	MH8	MH8	MH8	MH8	MH8	MH8	RFAB	MH8	RFAB, MH8	MH8
Assembly Site	MLA	MLA	TAI	MLA	MLA	MLA	CLARK-AT	MLA	MLA	MLA
Package Group	SSOP	SSOP	TSSOP	SSOP	SSOP	SSOP	QFN	SSOP	SSOP	SSOP
Package Designator	DKQ	DKQ	PWP	DKQ	DKQ	DKQ	RTE	DKQ	DKQ	DKQ
Pin Count	56	56	14	56	56	56	16	56	56	56

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TAS6422EQDKQRQ1 is qualified at MSL3 260C
- Qual Device TAS6424EQDKQRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TAS6422EQDKQRQ1	Qual Device: TAS6424EQDKQRQ1	QBS Process Reference: TPS55340QPWPRQ1	QBS Package, Product Reference: TAS6424QDKQRQ1	QBS Package, Product Reference: TAS6424QDKQRQ1	QBS Package Reference: TAS6424QDKQRQ1	QBS Process Reference: TPS2543QRTETQ1
Test Group A - Accelerated Environment Stress Tests														
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	3/Pass	-	-	-	3/Pass
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	-	-	-	3/0/0	3//4[1]	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0	3/231/1[3]	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	3/231/0	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-	3/231/0	3/231/2[2]	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	3/15/0	-	-	-	-
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	-	-	-	-	-
PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	-	1/45/0	-	-	1/45/0	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	1/45/0	-	-	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests														
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0	2/154/0	-	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	3/2400/0
Test Group C - Package Assembly Integrity Tests														
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0	1/30/0	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0	1/30/0	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	-	1/15/0	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	-	1/15/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	1/10/0	-	-	3/30/0	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests														



Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TAS6422EQDKQRQ1	Qual Device: TAS6424EQDKQRQ1	QBS Process Reference: TPS55340QPWPRQ1	QBS Package, Product Reference: TAS6424QDKQRQ1	QBS Package, Product Reference: TAS6424QDKQRQ1	QBS Package Reference: TAS6424QDKQRQ1	QBS Process Reference: TPS2543QRTETQ1
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests														
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	4000 Volts	-	-	-	1/3/0	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1000 Volts	-	-	-	-	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	-	-	1/3/0	1/3/0	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	750 Volts	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	1/3/0	1/6/0	1/6/0	-	-	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-	3/90/0
Additional Tests														
BLR	T1	-	-	-	Board Level Reliability - Temp Cycle	-40/125C	1000 Cycles	-	-	-	-	-	-	1/32/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2410-003

ZVEI ID: SEM-PW-13, SEM-PW-02, SEM-PW-03

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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